

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT5537928

SUBMISSION TYPE:	NEW ASSIGNMENT	
NATURE OF CONVEYANCE:	ASSIGNMENT	
CONVEYING PARTY DATA		
	Name	Execution Date
	GAKU IMAMURA	02/05/2019
	GENKI YOSHIKAWA	02/05/2019
	TAKASHI WASHIO	02/01/2019
RECEIVING PARTY DATA		
Name:	NATIONAL INSTITUTE FOR MATERIALS SCIENCE	
Street Address:	2-1, SENGEN 1-CHOME	
City:	TSUKUBA-SHI, IBARAKI	
State/Country:	JAPAN	
Postal Code:	305-0047	
PROPERTY NUMBERS Total: 1		
Property Type	Number	
Application Number:	16463585	
CORRESPONDENCE DATA		
Fax Number:	(202)739-3001	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>		
Phone:	202.739.3000	
Email:	patents@morganlewis.com, anne.sayles@morganlewis.com	
Correspondent Name:	ROBERT J. SMYTH	
Address Line 1:	1111 PENNSYLVANIA AVE NW	
Address Line 4:	WASHINGTON, D.C. 20004	
ATTORNEY DOCKET NUMBER:	100209-5018	
NAME OF SUBMITTER:	JEFFREY G. KILLIAN	
SIGNATURE:	/Jeffrey G. Killian/	
DATE SIGNED:	05/23/2019	
Total Attachments: 2		
source=100209-5018-Assignment#page1.tif		
source=100209-5018-Assignment#page2.tif		

A00/59V50/

Patent

ASSIGNMENT

WHEREAS WE, the below named inventors, (hereinafter referred to as "Assignors"), have made an invention entitled:

**SAMPLE IDENTIFICATION METHOD BASED ON CHEMICAL SENSOR MEASUREMENT, SAMPLE IDENTIFICATION DEVICE, AND INPUT
PARAMETER ESTIMATION METHOD**

for which WE filed PCT/IP2017/042060 on November 22, 2017; and

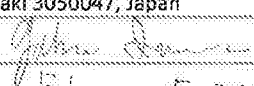
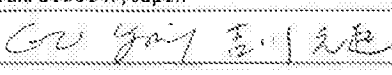
WHEREAS NATIONAL INSTITUTE FOR MATERIALS SCIENCE whose post office address is 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047, Japan (hereinafter referred to as "Assignee"), is desirous of securing the entire right, title, and interest in and to this invention in all countries throughout the world, and in and to the application of United States Letters Patent on this invention and the Letters Patent to be issued upon this application;

NOW THEREFORE, be it known that, for good and valuable consideration the receipt of which from Assignee is hereby acknowledged, WE, as assignors, have sold, assigned, transferred, and set over, and do hereby sell, assign, transfer, and set over unto the Assignee, its lawful successors and assigns, OUR entire right, title, and interest in and to this invention and this application, and all divisions, and continuations thereof, and all Letters Patent of the United States which may be granted thereon, and all reissues thereof, and all rights to claim priority on the basis of such applications, and all applications for Letters Patent which may hereafter be filed for this invention in any foreign country and all Letters Patent which may be granted on this invention in any foreign country, and all extensions, renewals, and reissues thereof; and WE hereby authorize and request the Director of Patents and Trademarks of the United States and any official of any foreign country whose duty it is to issue patents on applications as described above, to issue all Letters Patent of this invention to Assignee, its successors and assigns, in accordance with the terms of this Assignment;

AND, WE HEREBY covenant that WE have the full right to convey the interest assigned by this Assignment, and WE have not executed and will not execute any agreement in conflict with this Assignment;

AND, WE HEREBY further covenant and agree that WE will, without further consideration, communicate with Assignee, its successors and assigns, any facts known to US respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said Assignee, its successors or assigns, execute all divisional, continuation, and reissue applications, make all rightful oaths and generally do everything possible to aid Assignee, its successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the Assignee, its successors and assigns.

IN TESTIMONY WHEREOF, WE have hereunto set my hands.

Full Name of first Assignor	Gaku IMAMURA
Address	c/o NATIONAL INSTITUTE FOR MATERIALS SCIENCE, 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047, Japan
Signature	
Date	February 5, 2019
Full Name of second Assignor	Genki YOSHIKAWA
Address	c/o NATIONAL INSTITUTE FOR MATERIALS SCIENCE, 2-1, Sengen 1-chome, Tsukuba-shi, Ibaraki 3050047, Japan
Signature	
Date	February 5th, 2019

Patent

Full Name of first Assignor	Takashi WASHIO
Address	c/o OSAKA UNIVERSITY, 1-1, Yamadaoka, Suita-shi, Osaka 5650871, Japan
Signature	<i>Takashi Washio</i>
Date	<i>February, 1, 2019</i>

DB1/ 98267264.1

Morgan, Lewis & Bockius LLP

RECORDED: 05/23/2019

PATENT
REEL: 049283 FRAME: 0565